### the product:

Delivering cost effective soldering performance and reliability in both Wave <u>and</u> Selective / Rework Soldering processes





# Introduction

ALPHA® SACX<sup>™</sup> Plus 0307 is the next generation of our original, and very popular, SACX<sup>®</sup>0307 alloy. ALPHA® SACX<sup>™</sup> Plus 0307 is engineered to deliver the same high level of soldering performance and reliability as the original but it also exhibits minimal copper erosion when subjected to the long and hot exposure times common in selective soldering and rework processes.

Like the original **ALPHA® SACX™ Plus 0307** can be dropped in to most current SAC 305 wave and selective soldering processes. All this at a cost well below the higher silver bearing SAC 305.



## **Overview of the SACX® Family of Pb-free Alloys**

#### The SACX Family

Alloy	Description	Availability
	Basic alloy for use on single sided assemblies where moderate reliability in	Bars, wire, feeder
ALFHA SACA UTU/	required.	ingots
	Excellent soldering and reliability for either single sided or standard	Bars, wire, feeder
ALPHA SACA 0307	complexity dual sided assemblies.	ingots, spheres
	Similar wave soldering performance as standard SACX®0307 but engineered	Bars, wire, feeder
ALPHA SACA 0307 Plus	to minimize copper erosion during selective soldering and rework.	ingots
	Soldering performance and reliability similar to SAC305. For use on complex,	Bars, wire, feeder
ALPHA SACA 0807	dual sides assemblies where high wetting force is needed.	ingots
	Designed to produce a smooth, uniform pad finish while minimizing copper	
ALPHA SAUX HASL	erosion during plating.	Bars

- Alloys are engineered for optimal performance in specific processes or on certain types of assemblies
- Alloys are fully cross compatible

➢ For example, a component can be readily soldered to a SACX<sup>™</sup> Plus 0307 HASL finished pad using the SACX<sup>™</sup> Plus 0807 wave solder alloy

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## **Alloy Properties**

Material Property	Units	Vaculoy SACX0307 Plus
Solidus	Celsius	217
Liquidus	Celsius	228
Hardness	HV	14.1
Density	g/cc	7.33
Specific Heat Capacity	J/kg C	0.17
Stress at MAX Load	Mean	29.5
(N/mm²)	Std Dev	0.64
Elongation at failure (%)	Mean	21.8
	Std Dev	8.8
Thermal Expansion	(30 - 100C)/C x 10⊸	1.79
Coefficient	(100 - 150C)/C x 10⊸	2.30
Silver Content	%	0.3 +0.15/-0.05
Copper Content	%	0.70 +/-0.1
Lead Content	%	Max 0.1% *



\* Ultra Low Lead (ULL) version, <0.05% Pb, also available



## **Processing Parameters**

Wave Configuration	Process Parameter	Suggested Process Settings
	Pot temperature	255 - 265 Celsius (491 - 509 F)
	Conveyor speed	1.0 - 1.5 m/min (3.3 - 5 ft/min)
Cingle Weye	Contact time	2.3 - 2.8 seconds
Single wave	Wave Height	1/2 to 2/3 of board thickness
	Dross remo∨al	Once per 8 hour run time
	Copper Check	Every 8,000 boards until 40,000
	Pot temperature	255 - 265 Celsius (491 - 509 F)
	Conveyor speed	1.0 - 1.5 m/min (3.3 - 5 ft/min)
Dual Wave	Contact time	3.0 - 3.5 seconds
	Wave Height	1/2 to 2/3 of board thickness
	Dross remo∨al	Once per 8 hour run time



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## **Processing Parameters** – Copper Erosion

- Fountain selective soldering and rework systems, used to remove and replace components on PCBA's are normally operated at temperatures exceeding 260°C
- This procedure can expose the copper lead and land to the molten alloy for up to 60 (or more) seconds
- High silver alloys, not engineered to reduce copper erosion, can damage the copper land or lead making the assembly defective





## **Processing Parameters Copper Erosion**

Many studies have been that demonstrate the low Cu erosion rates of SACX<sup>™</sup> Plus 0307





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Insertion Time (sec)

40

20

50

SnCuNi-251

60

SACX0307

Source: iNEMI Cu Erosion Study, 2007

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Source: Large CEM

0.40 0.35

0.30 0.25

0.15

um/sec

Rate, 0.20

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40 Second Dwell Time

## **Processing Parameters** Dross Rate

600

ALPHA<sup>®</sup> SACX<sup>™</sup> Plus 0307 is manufactured using Cookson's proprietary Vaculoy process and also contains the same levels of antioxidant as the original SACX<sup>™</sup> Plus 0307.



Dross Rate SACX v SAC 305

## Soldering Performance - General Defects (bridges, skips, etc...)

#### Vaculoy SACX0307 Versus Sn/Cu based alloys



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## **Soldering Performance –** Hole Fill

• Hole Fill is strongly correlated with the wetting performance of the alloy/flux/finish combination.

• When wetting speed and force are high we should expect better hole fill -all other parameters being equal.

• Comparison of wetting balance test results are a strong indicator of hole fill capability.





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## **Soldering Performance** Hole Fill



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## **Reliability** – Thermal Fatigue Resistance

#### Test Results

• SACX0307 Solder Fillet - no fatigue cracks or grain delineation



Figure B2. No fatigue cracks can be seen in the heel fillet of the joint at higher magnifications

ALPHA SACX<sup>™</sup> Plus 0307 Plus contains many of the same constituents that make the original SACX<sup>™</sup> Plus 0307 exhibit equivalent or better reliability than other leading Pb-free alloys





SACX after cycling – no cracks

#### Sampling of results from customer thermal cycling tests

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Test Type	Lower	Upper	Cycles	Results	
Thermal Cycling	-40	125	2000	No difference between SACX and SAC305	
Thermal Cycling	-40	85	1000	Lower failure rate that SAC305	
Thermal Cycling	-40	90	500	0 failures	
Thermal Shock	-40	80	300	Lower failures than Sn/Cu/Ni	
Thermal Cycling	0	100	500	Passes requirements of PC manufacturer	
Thermal Cycling	-40	125	1000	Equivalent to SAC305 better than Sn/Cu/Ni	

#### 1206 Resistor Pull Tests





SACX<sup>™</sup>Plus 0307 Plus is made in each of our 3 global regions

Product Type	BAR
Product Group	BRC
Product Name	VAC



Alloy Code	Global Specification #
989	GLB-SAS-027
992	GLB-SAS-028

Item No#	Item Description	Product Name
148863	BRC 989 VAC SACX0307 Plus 1KG	ALPHA Vaculoy SACX®0307 Plus 1KG
149188	BRC 992 VAC SACX0300 Plus 1KG	ALPHA Vaculoy SACX®0300 Plus 1KG
148862	BRC 989 VAC SACX0307 Plus Chunk	ALPHA Vaculoy SACX®0307 Plus Chunk
149187	BRC 992 VAC SACX0300 Plus Chunk	ALPHA Vaculoy SACX®0300 Plus Chunk



Consult your local / regional manufacturing plant for special shape or size requests



# When to consider SACX<sup>™</sup> Plus 0307

- For simple to standard complexity dual sided assemblies
  - Assembler should always consider their most difficult assembly when selecting a single alloy

Assembly Type I	Assembly Type II	Assembly Type III	Assembly Type IV
Simple, single sided, FR2 / CEM-1 laminates	Dual sided FR-4 w/ PTH's, 1.6mm thick, up to 4 inner copper layers, metallized pad finishes	Complex, up to 12 inner copper layers, OSP pad finishes, all processing in air	>2.4mm thick, >12 inner copper layers, large high heat capacity components

- For assemblers who want a single alloy for both wave soldering and selective / rework soldering processes
- Users of lower Ag or Ag free alloys that:
  - Are not getting the soldering performance they need
  - Are seeing an increase in mechanical reliability related field failures

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## **Summary of Properties**

- Low silver content lowers alloy cost
- Engineered for use in Wave, Selective, Rework and Dip Tinning soldering applications
- Vaculoying process and unique additives minimize dross
- Fast wetting speeds and high wetting force results in excellent soldering across a wide variety of assemblies
- Silver and other additives result is strong, ductile solder joints for reliability similar or better than SAC305



## **Technical Bulletin and MSDS**



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Documents available from <u>www.alpha.cooksonelectronics.com</u> or contact your local Alpha<sup>®</sup> sales office

# Use the "SACX<sup>™</sup> Plus Family" map for guidance on which alloy to offer

	Assembly Type				
ver. 121208	Simple, single sided, FR2 / CEM- 1 laminates	Dual sided FR-4 w/ PTH's, 1.6mm thick, up to 4 inner copper layers, metallized pad finishes	Complex, up to 12 inner copper layers, OSP pad finishes, all processing in air	>2.4mm thick, >12 inner copper layers, large high heat capacity components	
es	TV Chassis (CRT)	PC Motherboard	High End PC Motherboard	Server board	
d X	Toys	Gamebox board	High End Gamebox board	Network Infrastructure	
Ĥ	Set top Box	PC Peripherals	Complex PC Peripherals	Telecom Base Station	
ice	DVD player	TV LCD/Plasma	High End TV LCD/Plasma		
ev	White Goods		Automotive (Pas.Comprt)		
	Audio System				
Assembly	ALPHA® SACX®	0107		Rework	
and	ALPHA® SACX®0307 Plus				
Rework	ALPHA® SACX® 0807				
	ALPHA® SAC305, 387, 405 *				
Reliability Require	ment				
Resistance	cycles	profile cycles	- 25°C to 125°C - standard and shock profile cycles	- 45°C to 125°C - standard and shock profile cycles	
HASI	ALPHA® SACX®HASL				
	* These allows are used in rework processes but are not optimized for that application				

#### **Relative Comparision of SACX Alloy Performance Attributes**

